## **Process / Product Change Notification**



### N° 1027-DISTI42-C4002348-Private

Dear Customer,

Please find attached our INFINEON Technologies PCN:

### Decommission of Newport, Wales wafer fab, as announced by the corporation on May 5th 2015 - Gen 12.7

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 05-November-2016.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-12, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Wolfgang Mayrhuber
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

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## Process / Product Change Notification

# infineon

### N° 1027-DISTI42-C4002348-Private

Decommission of Newport, Wales wafer fab, as announced by the corporation on May 5th 2015 - Gen 12.7

► Products affected:

See attached for affected parts.

Detailed Change Information:

**Subject:** Add Dresden 300MM as qualified Fab for Gen 12.7

Reason: Expansion of wafer production and wafer test capacity.

Description: Decommission of Newport, Wales wafer fab, as announced by the corporation on May 5th

2015 - Gen 12.7

### As the result of this change

	OLD	NEW
Site	Infineon Technologies Newport Limited	TowerJazz or Infineon Technologies Newport Limited or Infineon Technologies AG, Dresden, Germany

▶ Product Identification:

Wafer fab origins will not be distinguished through the external part marking or shipping labels, however, based on the assembly lot code and marked on the device. IFX internal systems will be able to trace the site of the wafer late used to produce the final product.

be able to trace the site of the wafer lots used to produce the final product.

▶ Impact of Change: No changes to form, fit, or function. The package outline remains the same. Datasheet

specifications will not be changed. The package bill of material and the location for assembly

and final test will not change.

► Attachments: 1027-DISTI42-C4002348-AffectedParts.xlsx

► Time Schedule:

Final qualification report: Available

First samples available: On Request

Intended start of delivery: 17-November-2016

If you have any questions, please do not hesitate to contact your local Sales office.

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Sales Name	SP number	OPN	Package
IRFP7430PBF	SP001554970	IRFP7430PBF	TO247
IRFB7430PBF	SP001551786	IRFB7430PBF	TO220
IRFB7434PBF	SP001575514	IRFB7434PBF	TO220
IRFB7437PBF	SP001556080	IRFB7437PBF	TO220
IRFB7440PBF	SP001566700	IRFB7440PBF	TO220
IRFB7446PBF	SP001577760	IRFB7446PBF	TO220
IRFS7437TRLPBF	SP001550174	IRFS7437TRLPBF	D2PAK
IRFS7440TRLPBF	SP001552344	IRFS7440TRLPBF	D2PAK
IRFR7446TRPBF	SP001557906	IRFR7446TRPBF	DPAK
IRFS7434TRL7PP	SP001557462	IRFS7434TRL7PP	D2PAK7P
IRFS7434TRLPBF	SP001578486	IRFS7434TRLPBF	D2PAK
IRFS7437TRL7PP	SP001557510	IRFS7437TRL7PP	D2PAK7P
IRFS7430TRL7PP	SP001565252	IRFS7430TRL7PP	D2PAK7P
IRFS7430TRLPBF	SP001571706	IRFS7430TRLPBF	D2PAK
IRFSL7440PBF	SP001573650	IRFSL7440PBF	TO262
IRFS7430-7PPBF	SP001557480	IRFS7430-7PPBF	D2PAK7P